

1. Record Nr.	UNINA9910876617903321
Titolo	Nano and micromachining // edited by J. Paulo Davim, Mark J. Jackson
Pubbl/distr/stampa	Hoboken, NJ, : John Wiley & Sons, 2009
ISBN	1-282-16549-6 9786612165498 0-470-61180-4 0-470-61027-1
Descrizione fisica	1 online resource (224 p.)
Collana	ISTE
Altri autori (Persone)	DavimJ. Paulo JacksonMark J
Disciplina	620.5 620/.5
Soggetti	Nanotechnology Micromachining
Lingua di pubblicazione	Inglese
Formato	Materiale a stampa
Livello bibliografico	Monografia
Note generali	Description based upon print version of record.
Nota di bibliografia	Includes bibliographical references and index.
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Sommario/riassunto

This book provides the fundamentals and recent advances in nano and micromachining for modern manufacturing engineering. It begins by outlining nanomachining before discussing various advances in field and machining processes. The coverage concludes with an evaluation of subsurface damages in nano and micromachining and a presentation of applications in industry. As such, this book serves both as a useful classroom text for engineering and machining courses at the undergraduate and graduate level, and as a reference for academics and engineers in these areas.
